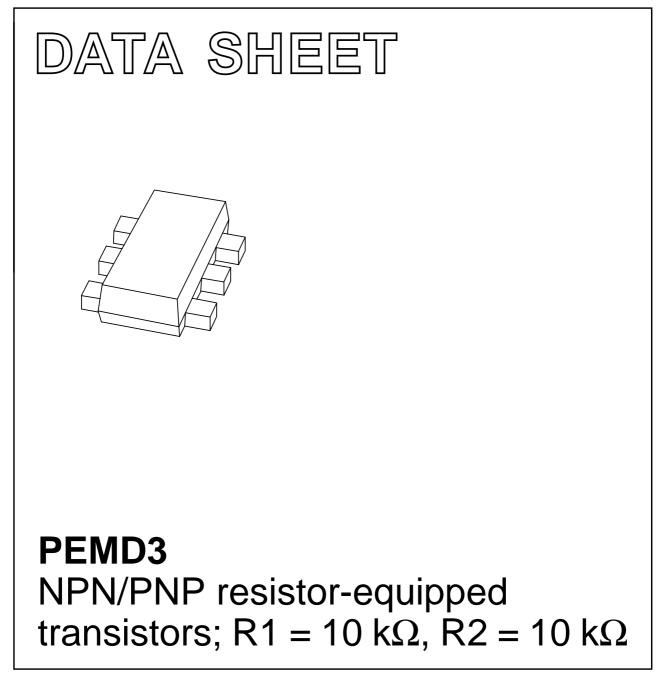
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of 2001 Sep 13 2001 Nov 07



PEMD3

FEATURES

- 300 mW total power dissipation
- Very small 1.6 mm x 1.2 mm ultra thin package
- Excellent coplanarity due to straight leads
- Replaces two SC-75/SC-89 packaged transistors on same PCB area
- Reduces required PCB area
- Reduced pick and place costs.

APPLICATIONS

- General purpose switching and amplification
- Inverter and interface circuits
- Circuit driver.

DESCRIPTION

NPN/PNP resistor-equipped transistors in a SOT666 plastic package.

MARKING

TYPE NUMBER	MARKING CODE		
PEMD3	D3		

QUICK REFERENCE DATA

SYMBOL	PARAMETER	MAX.	UNIT
V _{CEO}	collector-emitter voltage	50	V
I _{CM}	peak collector current	100	mA
TR1	NPN	_	-
TR2	PNP	—	-
R1	bias resistor	10	kΩ
R2	bias resistor	10	kΩ

PINNING

PIN	DESCRIPTION		
1, 4	emitter	TR1; TR2	
2, 5	base	TR1; TR2	
6, 3	collector	TR1; TR2	

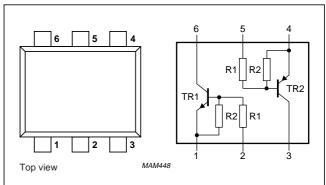


Fig.1 Simplified outline (SOT666) and symbol.

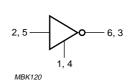


Fig.2 Equivalent inverter symbol.

PEMD3

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
Per transistor; for the PNP transistor with negative polarity					
V _{CBO}	collector-base voltage	open emitter	_	50	V
V _{CEO}	collector-emitter voltage	open base	_	50	V
V _{EBO}	emitter-base voltage	open collector	-	10	V
VI	input voltage TR1				
	positive		_	+40	V
	negative		_	-10	V
	input voltage TR2				
	positive		_	+10	V
	negative		_	-40	V
lo	output current (DC)		-	100	mA
I _{CM}	peak collector current		_	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	-	200	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		_	150	°C
T _{amb}	operating ambient temperature		-65	+150	°C
Per device					
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C; note 1	_	300	mW

Note

1. Transistor mounted on an FR4 printed-circuit board.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R _{th j-a}	thermal resistance from junction to ambient	notes 1 and 2	416	K/W	

Notes

1. Transistor mounted on an FR4 printed-circuit board.

2. The only recommended soldering method is reflow soldering.

PEMD3

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Per transist	Per transistor; for the PNP transistor with negative polarity					
I _{CBO}	collector-base cut-off current	$V_{CB} = 50 \text{ V}; I_E = 0$	-	-	100	nA
I _{CEO}	collector-emitter cut-off current	$V_{CE} = 50 \text{ V}; I_B = 0$	_	-	1	μA
		V _{CE} = 30 V; I _B = 0; T _j = 150 °C	_	-	50	μA
I _{EBO}	emitter-base cut-off current	$V_{EB} = 5 V; I_C = 0$	_	-	400	μA
h _{FE}	DC current gain	$V_{CE} = 5 \text{ V}; I_{C} = 5 \text{ mA}$	30	-	_	
V _{CEsat}	saturation voltage	I _C = 10 mA; I _B = 0.5 mA	_	-	150	mV
V _{i(off)}	input off voltage	$V_{CE} = 5 \text{ V}; \text{ I}_{C} = 100 \mu\text{A}$	_	1.1	0.8	V
V _{i(on)}	input on voltage	V _{CE} = 0.3 V; I _C = 10 mA				
	TR1 (NPN)		2.5	1.1	_	V
	TR2 (PNP)		2.5	1.8	_	V
R ₁	input resistor		7	10	13	kΩ
R2 R1	resistor ratio		0.8	1	1.2	
C _c	collector capacitance	I _E = i _e = 0; V _{CB} = 10 V;				
	TR1 (NPN)	f = 1 MHz	_	_	2.5	pF
	TR2 (PNP)		-	-	3	pF

PEMD3

NPN/PNP resistor-equipped transistors; R1 = 10 k Ω , R2 = 10 k Ω

MGW369 MGW368 10³ h_{FE} VCEsat (V) 10² (3) 10⁻¹ 10 (2) (3) 10⁻² 10² 10² 10^{-} 1 10 10 I_C (mA) 1 I_C (mA) TR1 (NPN); $V_{CE} = 5 V$. **TR1 (NPN);** I_C/I_B = 20. (1) T_{amb} = 150 °C. (1) T_{amb} = 100 °C. (2) T_{amb} = 25 °C. (2) T_{amb} = 25 °C. (3) $T_{amb} = -40 \ ^{\circ}C.$ (3) $T_{amb} = -40 \ ^{\circ}C.$ Fig.3 DC current gain as a function of collector Fig.4 Collector-emitter saturation voltage as a current; typical values. function of collector current; typical values. MGW371 MGW370 10² 10 V_{i(on)} V_{i(off)} (V) (V) 10 (1) Т (2) 1 (3) П (3) -----1 10⁻¹ 10⁻¹ 10-2 10⁻¹ 10⁻¹ 1 10 1 10 10² I_C (mA) I_C (mA) TR1 (NPN); V_{CE} = 5 V. TR1 (NPN); V_{CE} = 0.3 V. (1) $T_{amb} = -40 \ ^{\circ}C.$ (1) $T_{amb} = -40 \ ^{\circ}C.$ (2) $T_{amb} = 25 \circ C$. (2) T_{amb} = 25 °C. (3) $T_{amb} = 100 \ ^{\circ}C.$ (3) T_{amb} = 100 °C. Fig.5 Input-off voltage as a function of collector Fig.6 Input-on voltage as a function of collector

current; typical values.

2001 Nov 07

current; typical values.

MGW373 MGW372 10³ h_{FE} VCEsat (V) 10² (3)-10⁻¹ (2) 10 (3) -10⁻² I_{C} (mA) $^{-10^{2}}$ -10² -10-_1 -10 _1 -10I_C (mA) **TR2 (PNP);** $V_{CE} = -5 V$. **TR2 (PNP);** I_C/I_B = 20. (1) T_{amb} = 150 °C. (1) T_{amb} = 100 °C. (2) T_{amb} = 25 °C. (2) T_{amb} = 25 °C. (3) $T_{amb} = -40 \ ^{\circ}C.$ (3) $T_{amb} = -40 \ ^{\circ}C.$ Fig.7 DC current gain as a function of collector Fig.8 Collector-emitter saturation voltage as a current; typical values. function of collector current; typical values. MGW375 MGW374 -10² -10V_{i(on)} V_{i(off)} (V) (V) -10 (1) (2) -1 (3) (2 (3) ------1 -10⁻¹ -10⁻¹ $I_{\rm C}$ (mA) -10^2 -10-2 -10⁻¹ -10 -10^{-1} -1 -1 -10 I_C (mA) TR2 (PNP); V_{CE} = -5 V. TR2 (PNP); V_{CE} = -0.3 V. (1) $T_{amb} = -40 \ ^{\circ}C.$ (1) $T_{amb} = -40 \ ^{\circ}C$. (2) $T_{amb} = 25 \circ C$. (2) T_{amb} = 25 °C. (3) $T_{amb} = 100 \ ^{\circ}C.$ (3) T_{amb} = 100 °C. Fig.9 Input-off voltage as a function of collector Fig.10 Input-on voltage as a function of collector current; typical values. current; typical values.

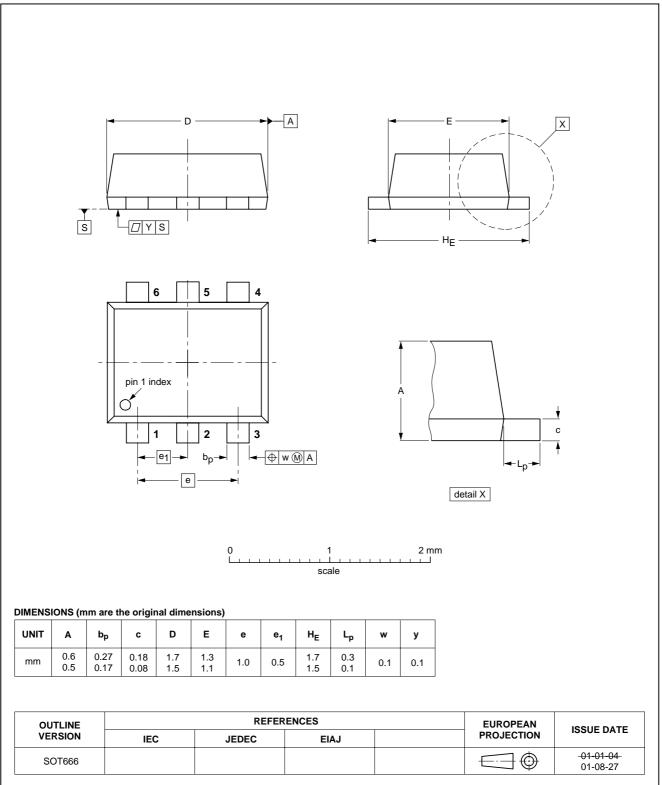
PEMD3

PEMD3

NPN/PNP resistor-equipped transistors; R1 = 10 k Ω , R2 = 10 k Ω

PACKAGE OUTLINE

Plastic surface mounted package; 6 leads



SOT666

PEMD3

DATA SHEET STATUS

DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITIONS
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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